



Microfabrication group in 2004

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Research themes in microfabrication

- Silicon, glass and polymer processing
 - Etching (wet, plasma, electrochemical)
 - Bonding (anodic, adhesive)
 - Thin films (Pt, DLC, ECD, LPD, SOG,...)
- Fluidic, thermal and chemical applications



Microfluidic benefits

Small devices are faster

==>reduced analysis time

==>thermal speed superior

New possibilities arise at small scales

==>surface tension and electrical forces
can be beneficially used

==>high sensitivity at low flow rate



Microfabrication precision

==>new nozzle designs

Microfabrication economics

==>disposable chips, ease of operation,
less contamination

==>reusable chips, cheap compared with
macroscopic counterparts



Reduced sample amounts required

==> new possibilities in bioanalysis

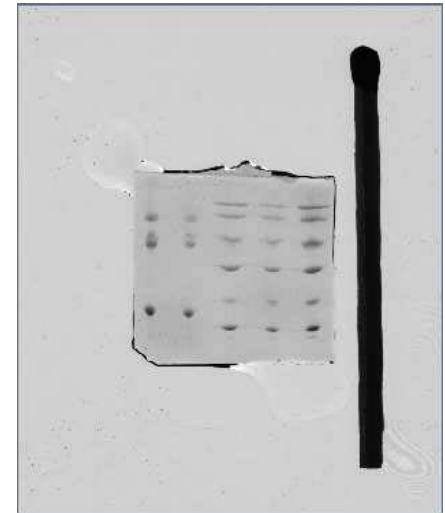
Different functions can be integrated

==> fewer analytical steps



Miniturized protein chip

- milli- and microfabrication
- two separation steps on one chip
- separation in 30 minutes vs. 24 hours in macrosystem



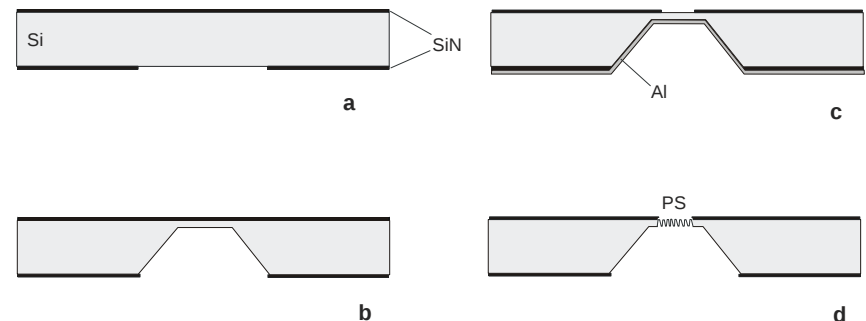
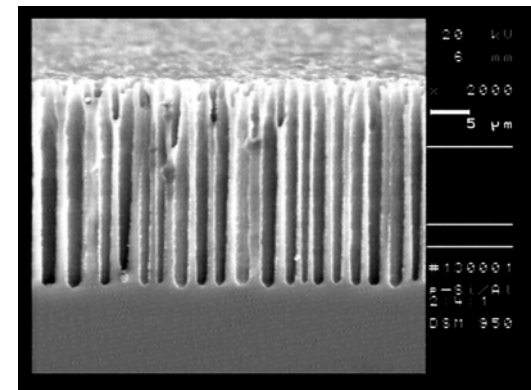
Porous silicon membranes

Filtration of microbeads
in biomedical samples.

Integrated, on-chip
micromembranes

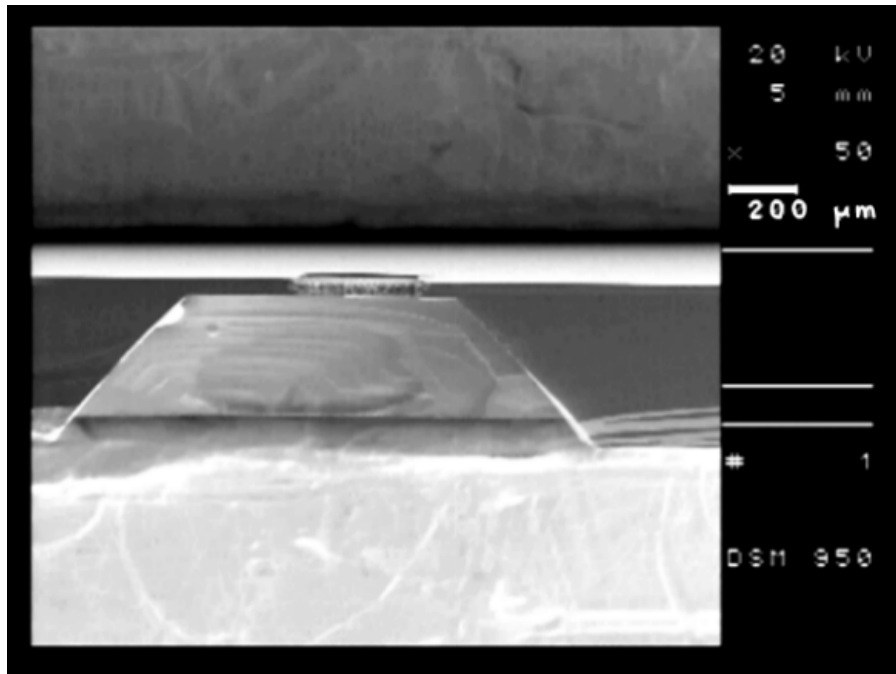
Electrochemical etching –
adjustable pore size

- Lithography
- Back-side etching in TMAH
- Porous layer formation in HF: DMSO



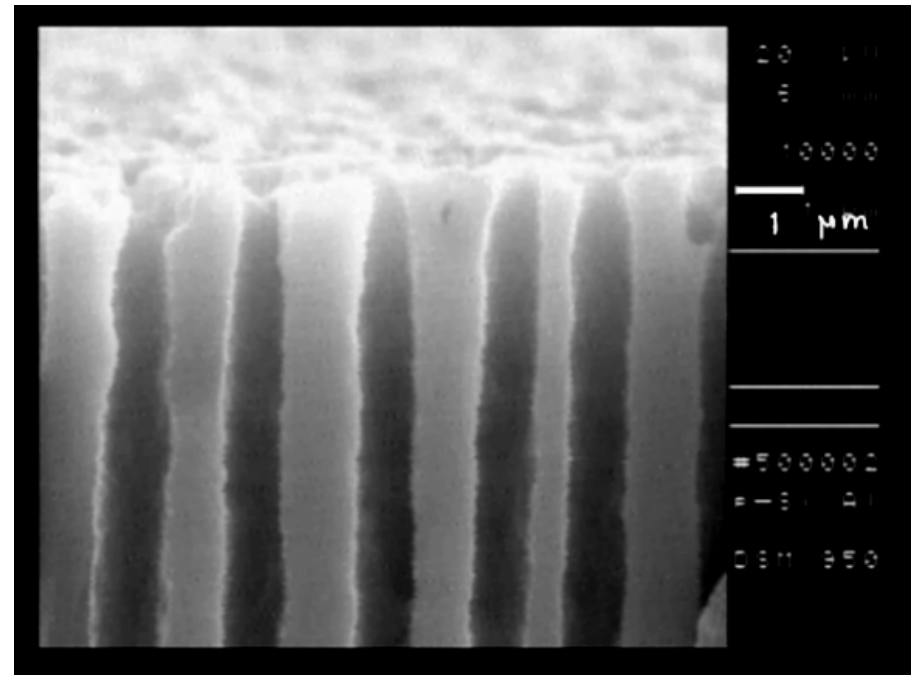


Porous silicon membranes



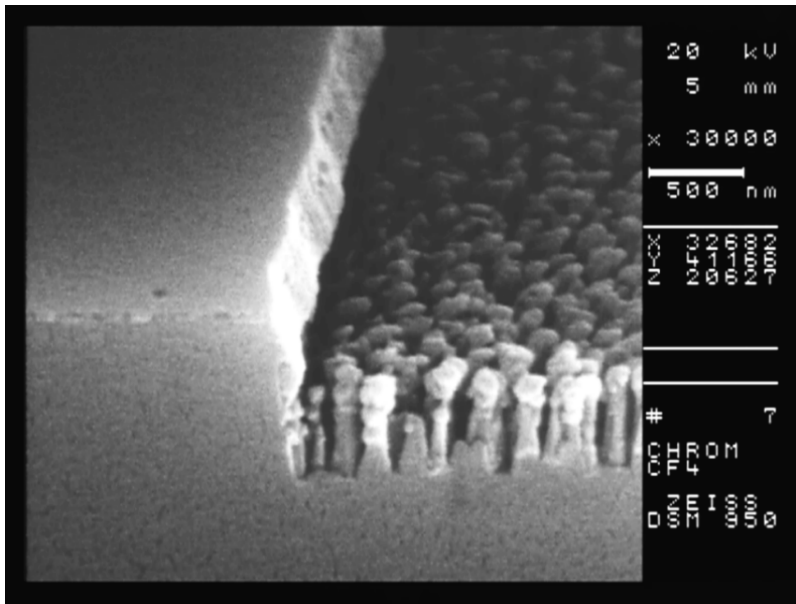
40 μm thick porous membrane

macropore cross-section $< 1 \mu\text{m}$



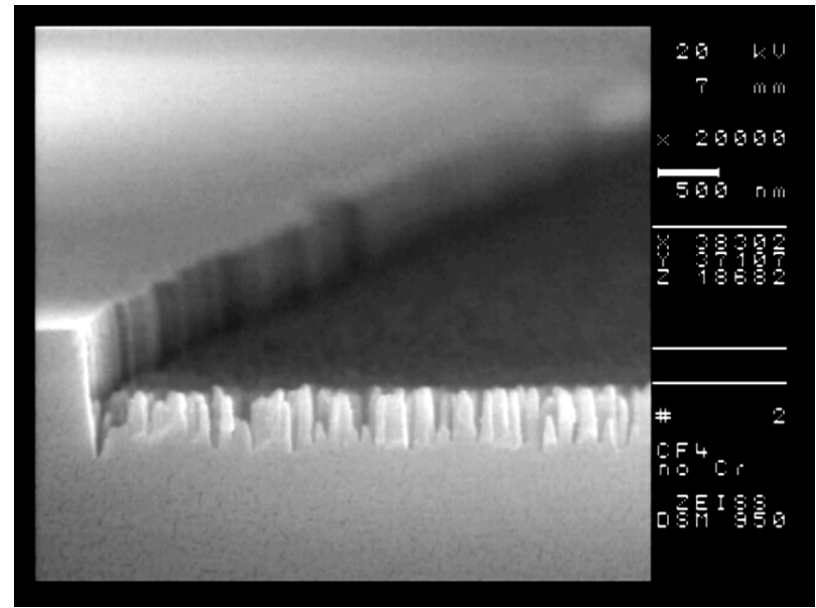


Formation of nanoporous glass



Plasma etching of pyrex glass in CF_4/Ar gases

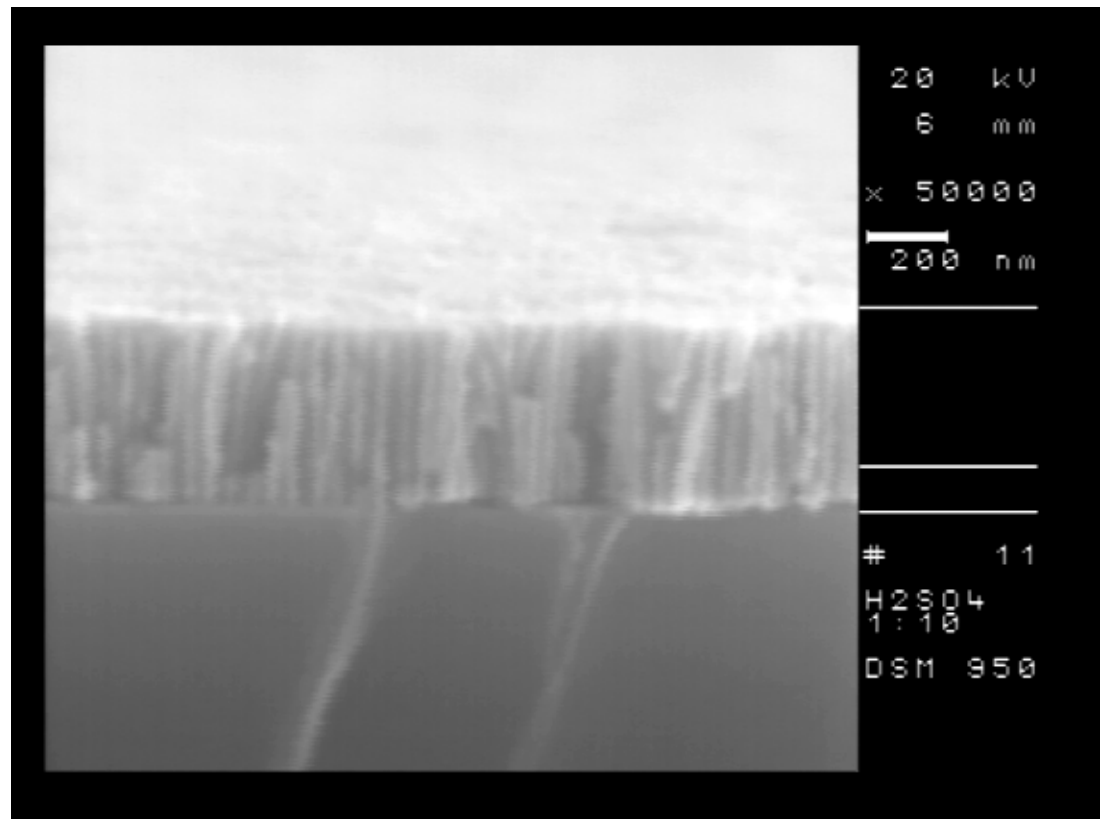
pillars of 500 nm high and 60—120 nm in cross-section





Formation of nanoporous alumina by electrochemical etching

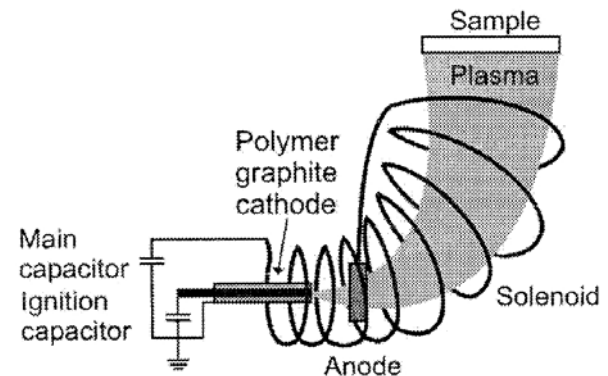
- uniform pore distribution
- pore size: 50 nm
- application as a fluidic filter or as etching mask





Diamond-like carbon, DLC

- DLC deposited at University of Helsinki
- Filtered Pulsed Arc Deposition FPAD
- room temperature deposition
- 85% sp^3 hybridized, 80 GPa hardness
- thick layers (up to 100 μm)





DLC-PDMS-h material properties

- Diamond surface properties:
 - scratch resistance
 - hydrophobic nature
 - 0.15° sliding angle
- Non-porous
- Hardness 20 GPa (vs. 80 GPa for DLC)
- Thermal stability up to 400°C

DLC-PDMS-h processing

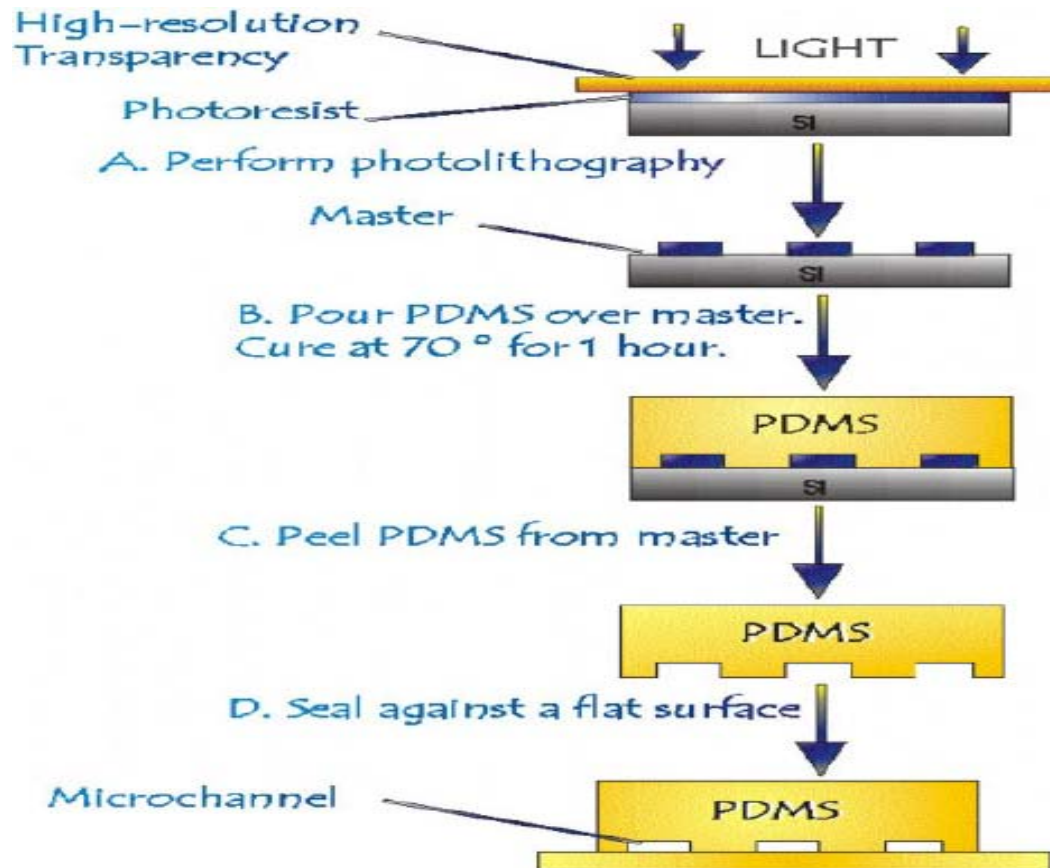
-hydrophobicity adjustment by plasmas



a) As deposited b) O₂ plasma treated c) CF₄/Ar plasma treated

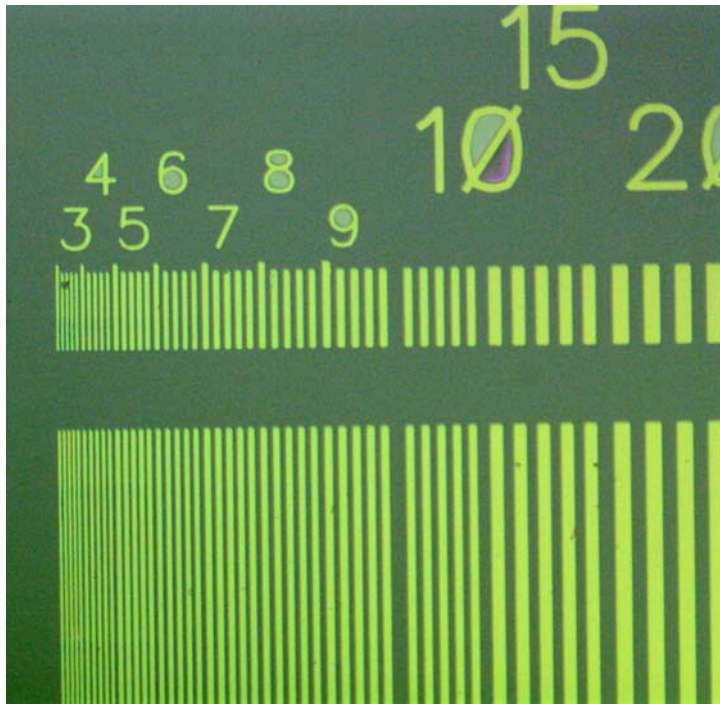


DLC in mold masters





DLC-PDMS-hybrid patterning by lift-off



3 μm minimum
linewidth



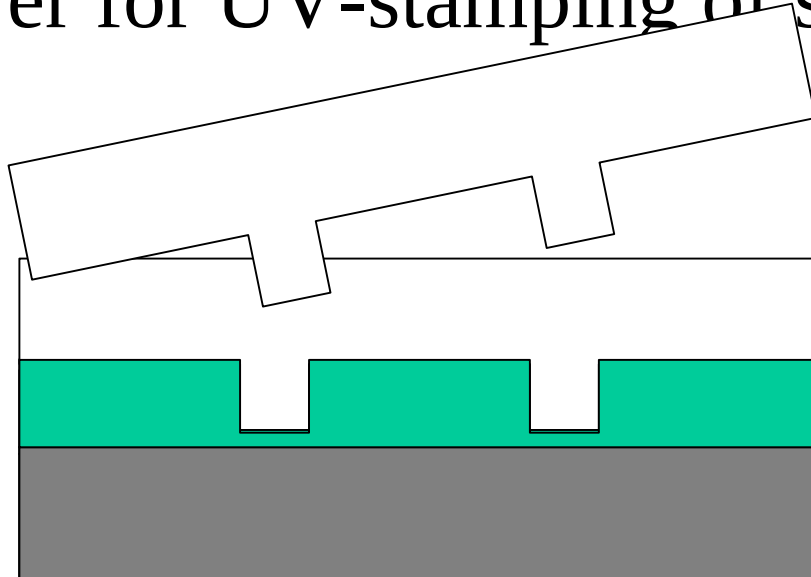
Photoactive hybrid glasses

- act as negative resists (not unlike SU-8)
- siloxane-based (oxide character)
- spin-coated
- 400 nm to 400 μm thickness
- thermally stable up to 450°C
- resistant to most chemicals used in microfabrication
- hydrophobic surfaces



Embossing polymers

- optical transparency and antisticking nature of DLC-PDMS-h are utilized in antisticking layer for UV-stamping of siloxanes



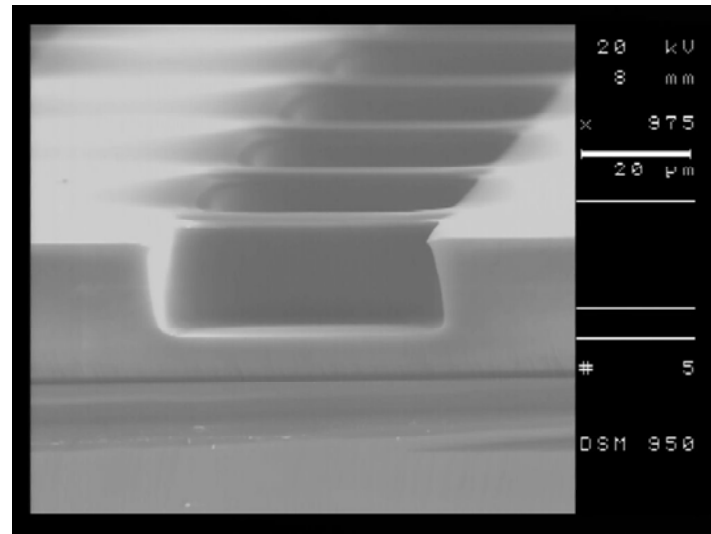
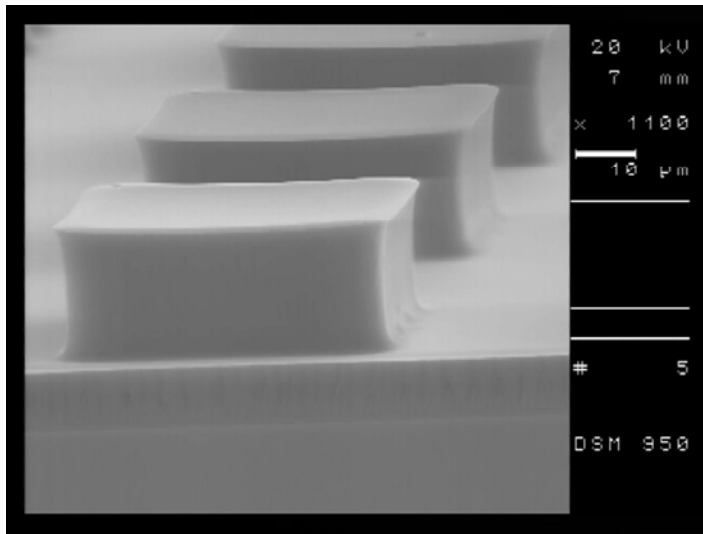
stamp release

stamping, UV-exposure

spin siloxane on the substrate



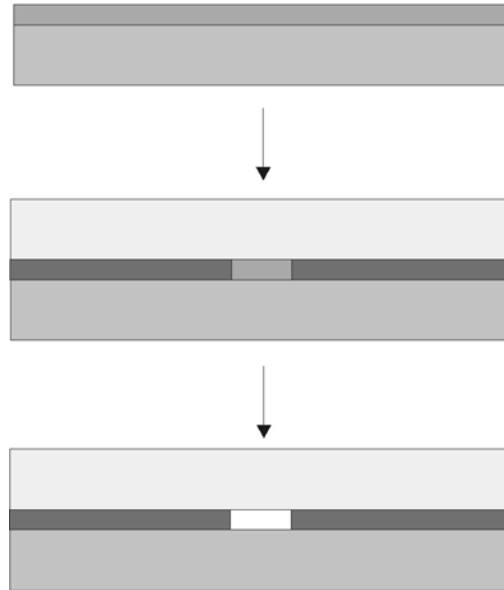
Embossing results





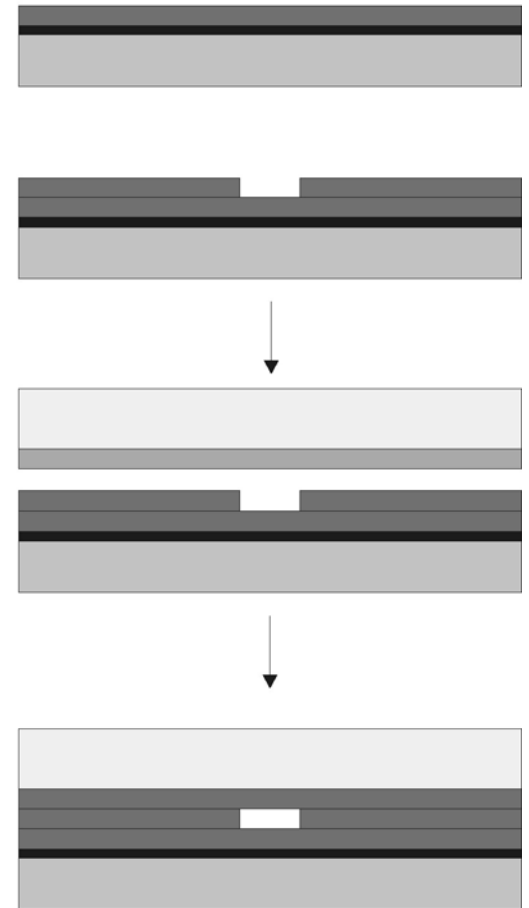
SU-8 adhesive bonding

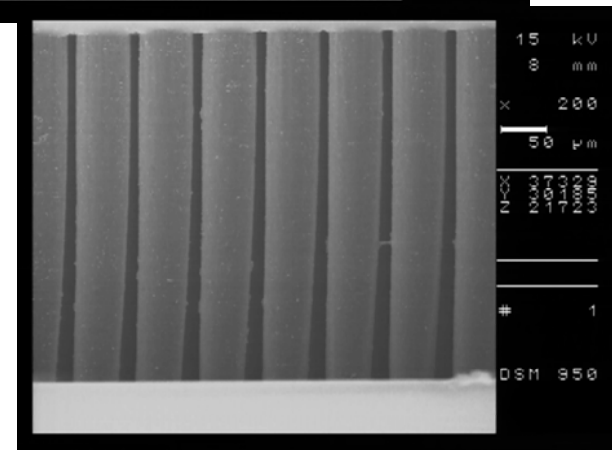
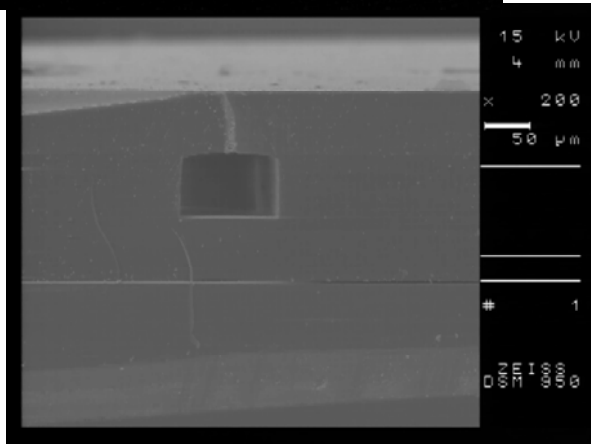
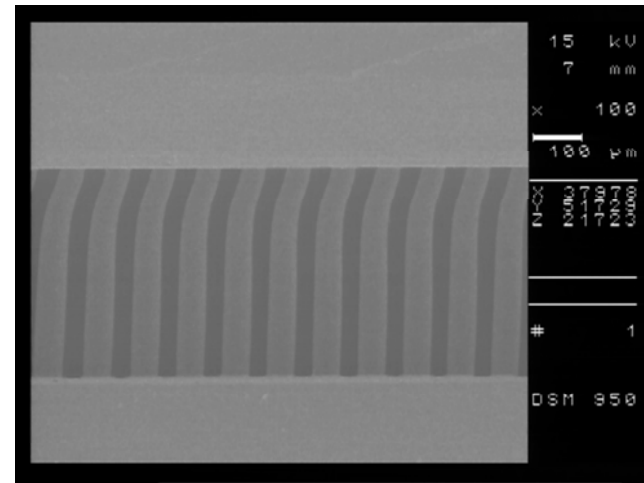
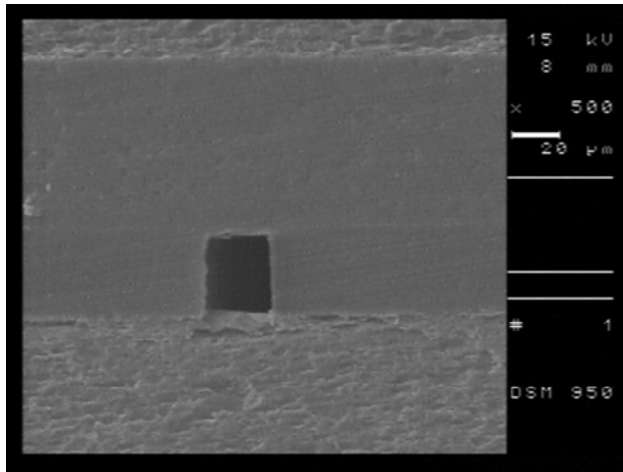
Process flow A



- Unexposed SU-8
- Cross-linked SU-8
- Silicon wafer
- Glass wafer
- Thermal oxide

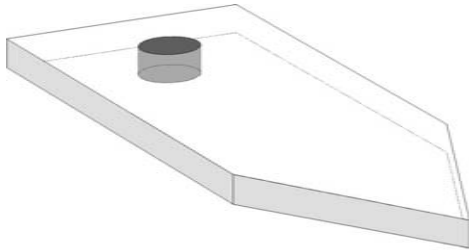
Process flow B



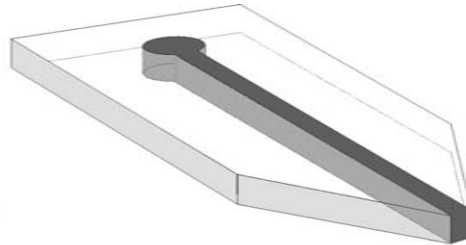




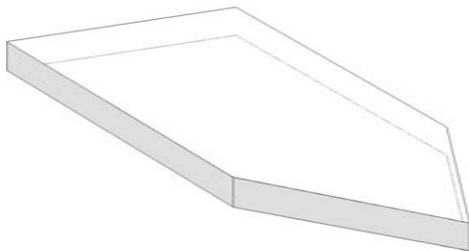
ESI in SU-8



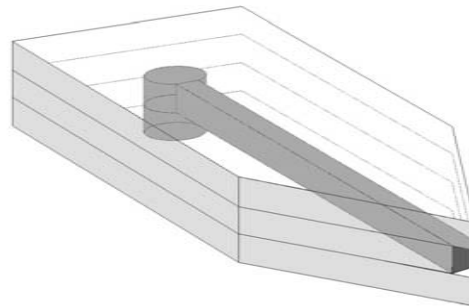
1st layer of SU-8



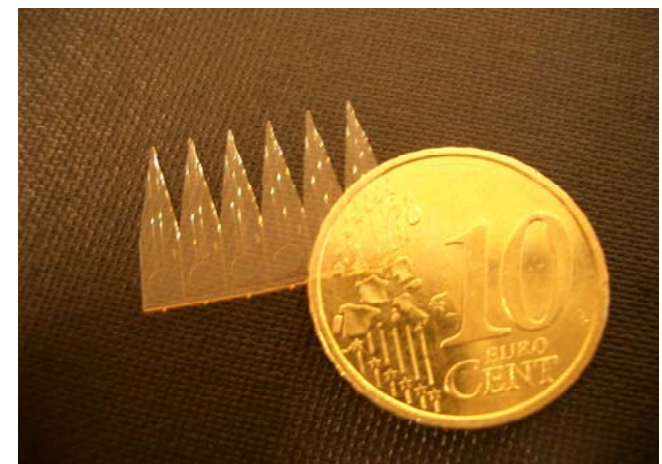
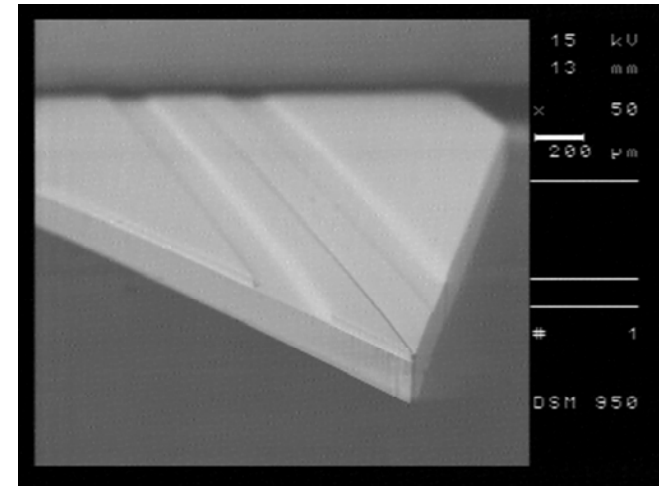
2nd layer of SU-8



3rd layer of SU-8

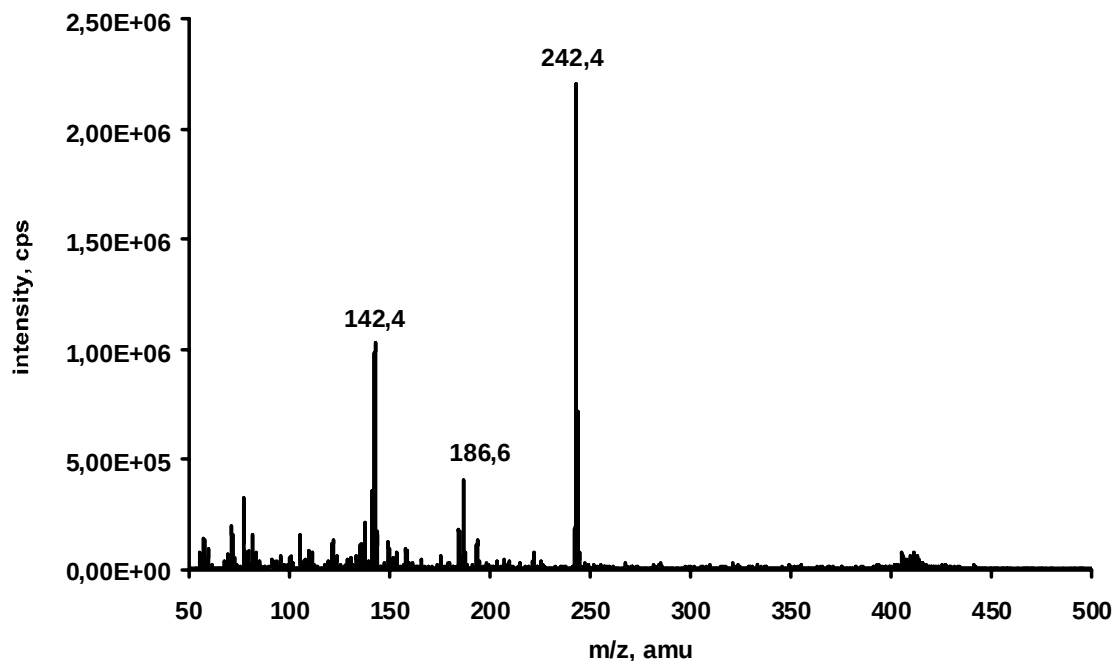


Ready device



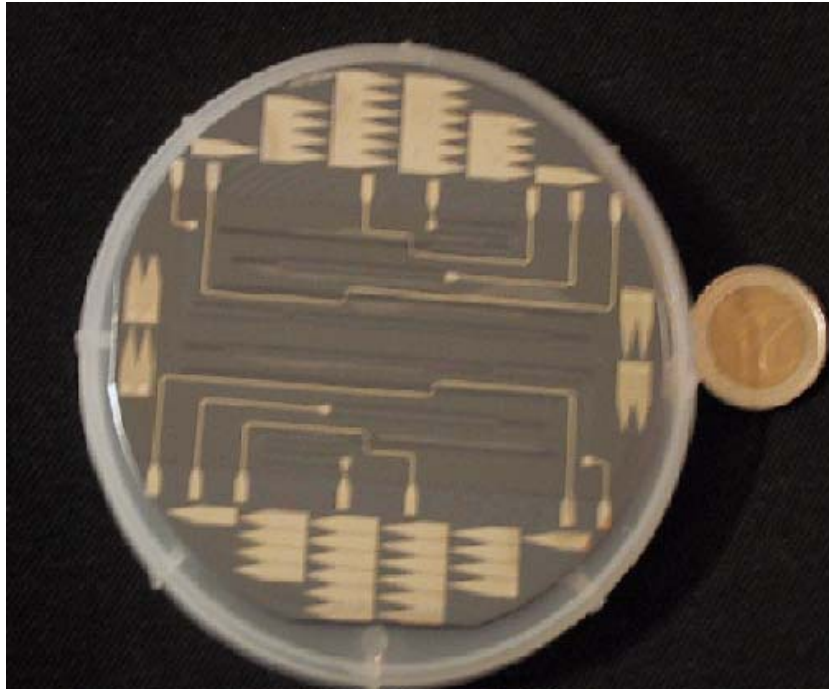


Tetra-n-butylammonium $[M]^+=242$ at 2 μM concentration. Methanol:water 4:1. Microtip $10\mu\text{m} \times 20\mu\text{m}$.



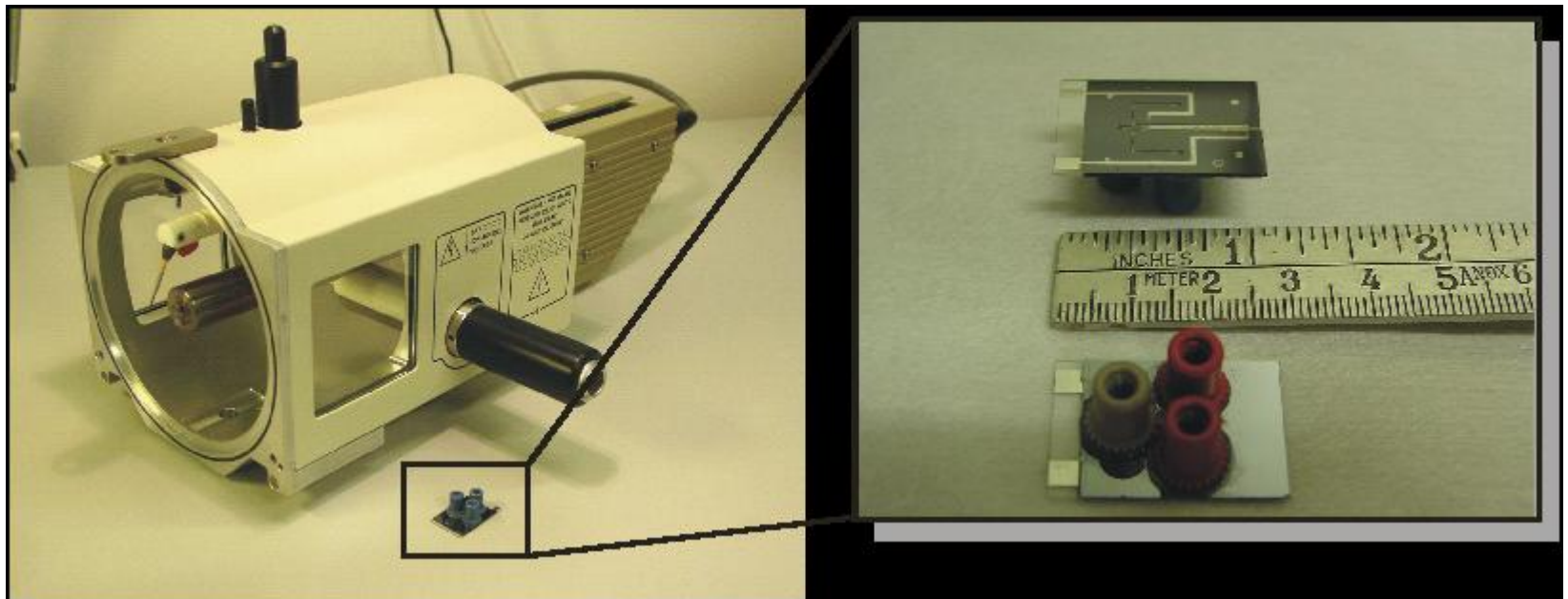


ITP microfluidic chips with integrated platinum electrodes

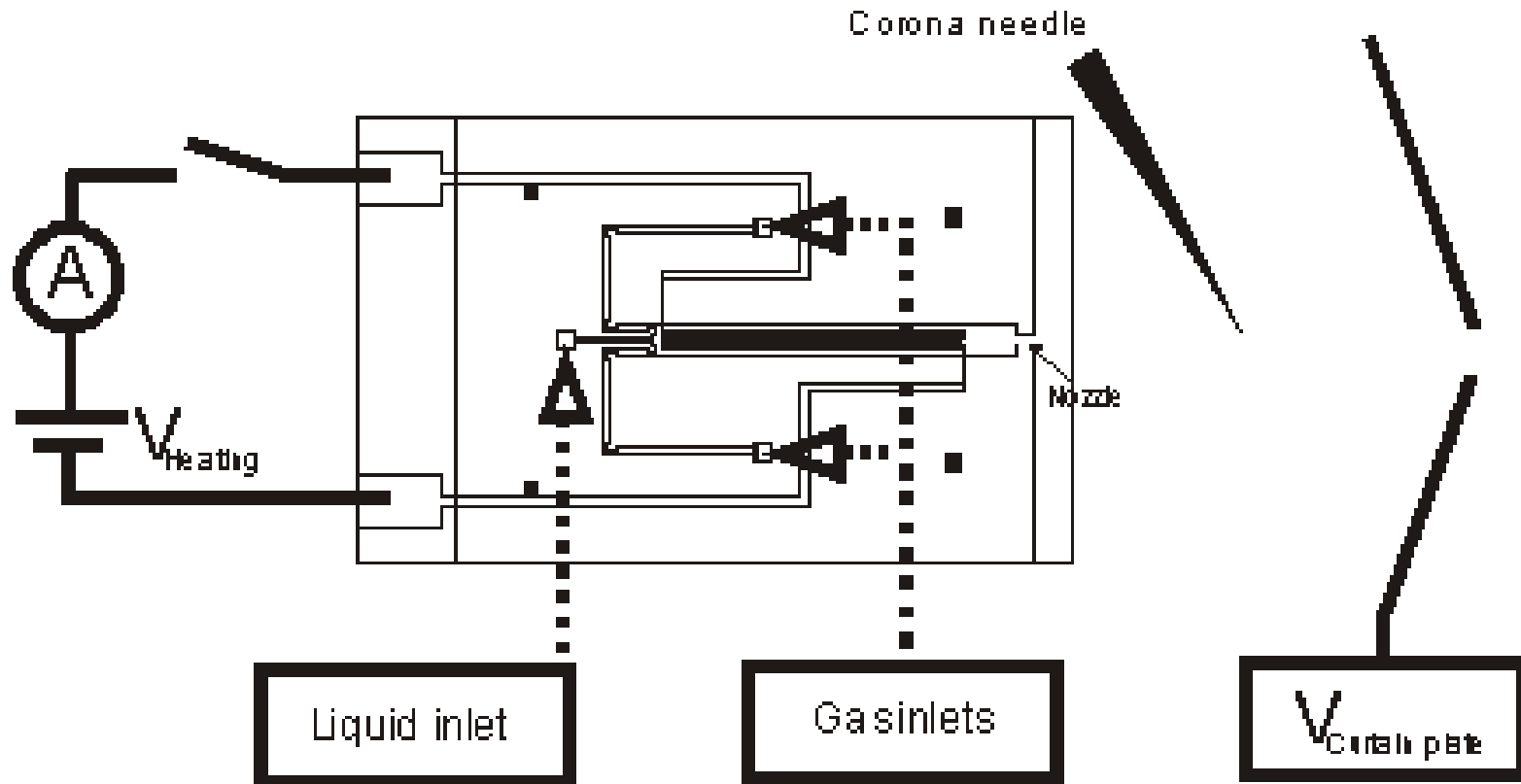


Ristola, R., Tuomikoski, S., Franssila, S., Submitted.

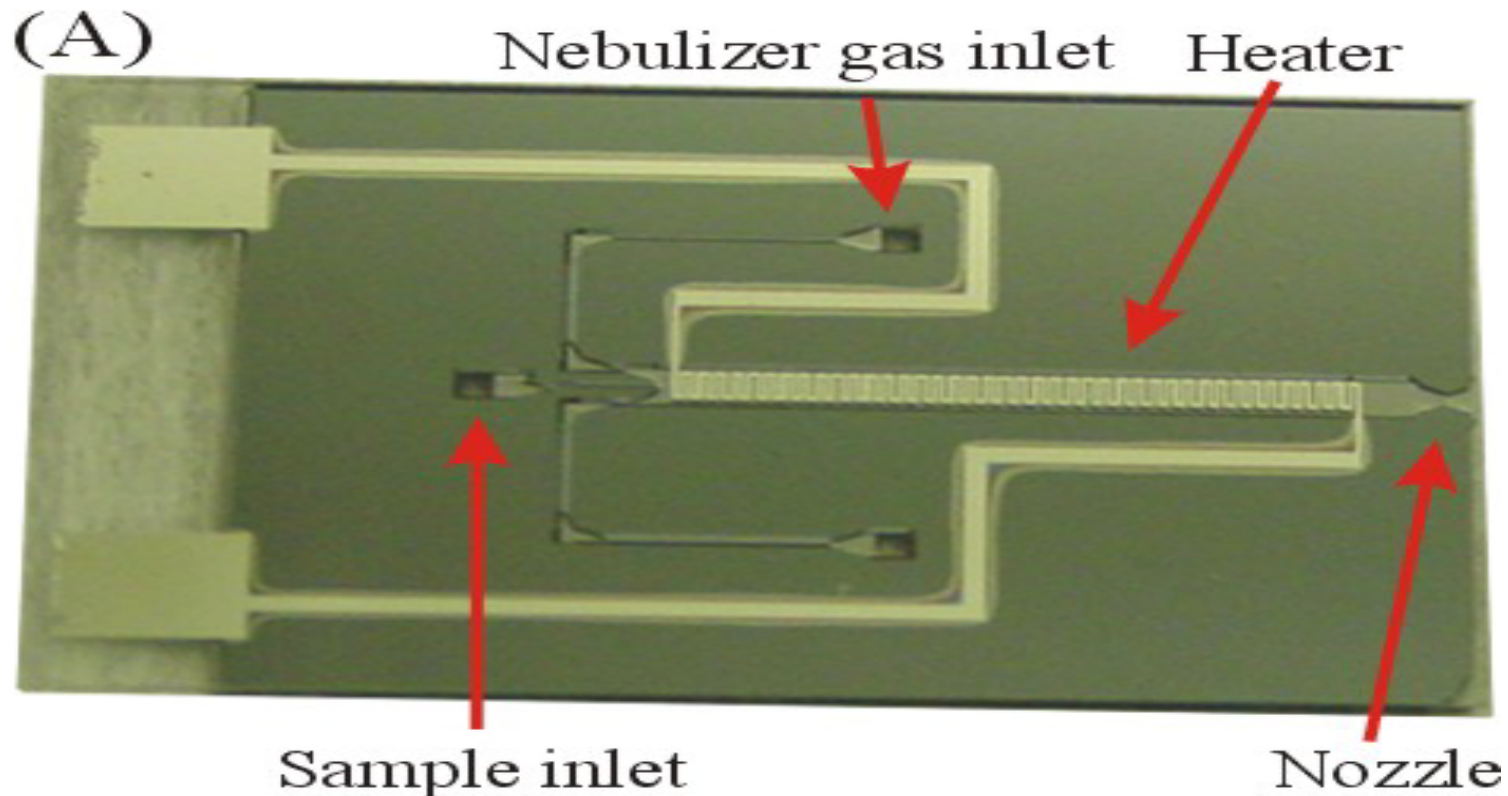
μ APCI source vs. macroAPCI source (PE Sciex API-300)



Atmospheric Pressure Chemical Ionization



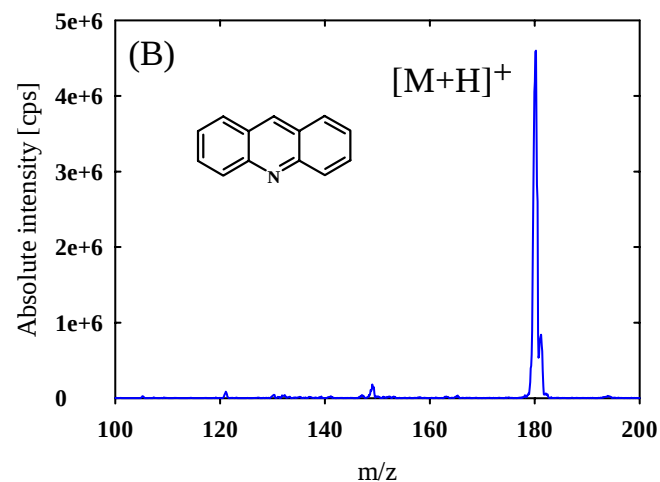
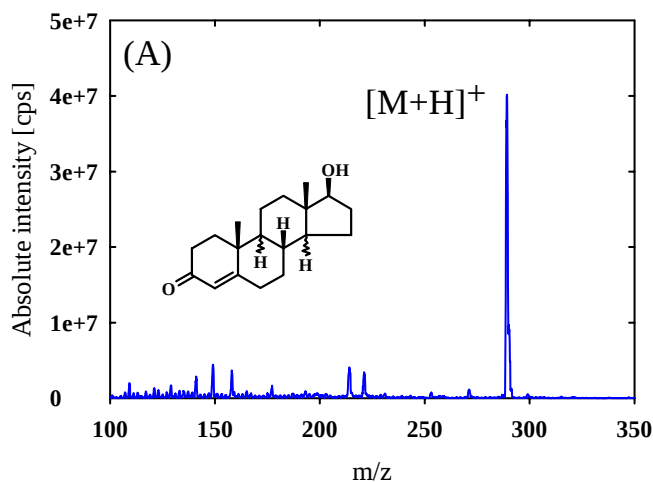
Ionization (APCI) chip





Mass spectra: excellent

a) testosterone; b) acridine



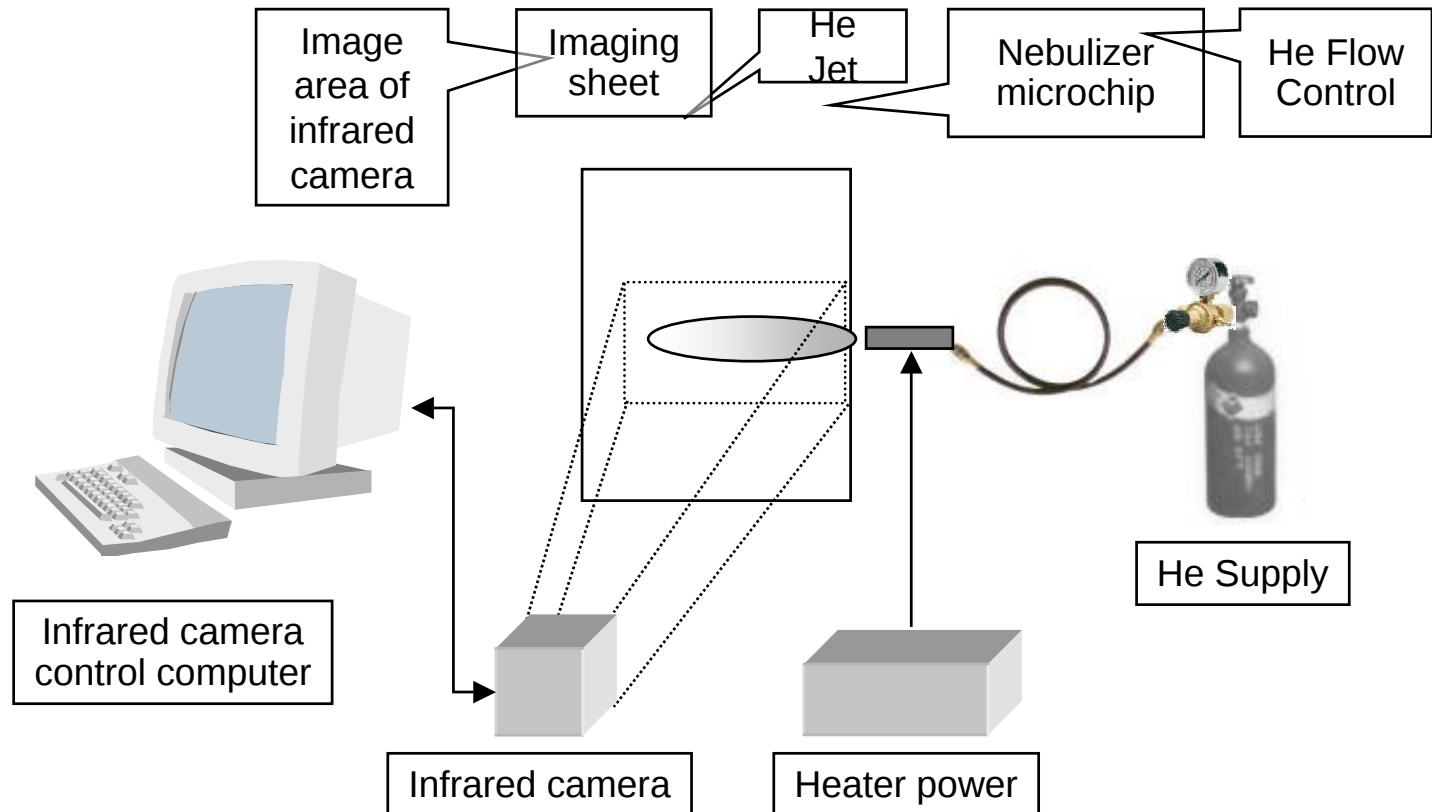


Detection limits

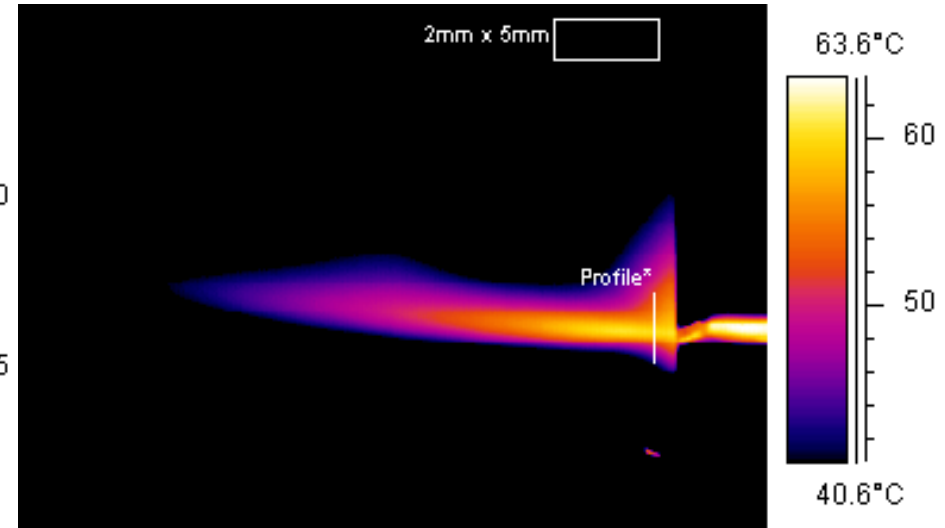
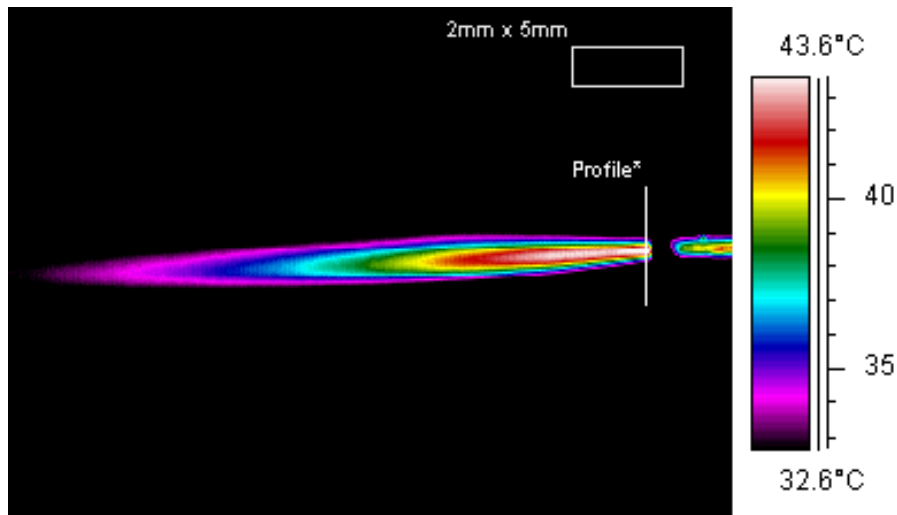
	flow rate	detection limit	mass flow
	[$\mu\text{l}/\text{min}$]	[mol/l]	[g/s]
μAPCI	6.2	$5 * 10^{-9}$	$0.1 * 10^{-12}$
macroAPCI	6.2	$75 * 10^{-9}$	$1.4 * 10^{-12}$
macroAPCI	1000	$5 * 10^{-9}$	$14.9 * 10^{-12}$



Jet shape measurement set-up

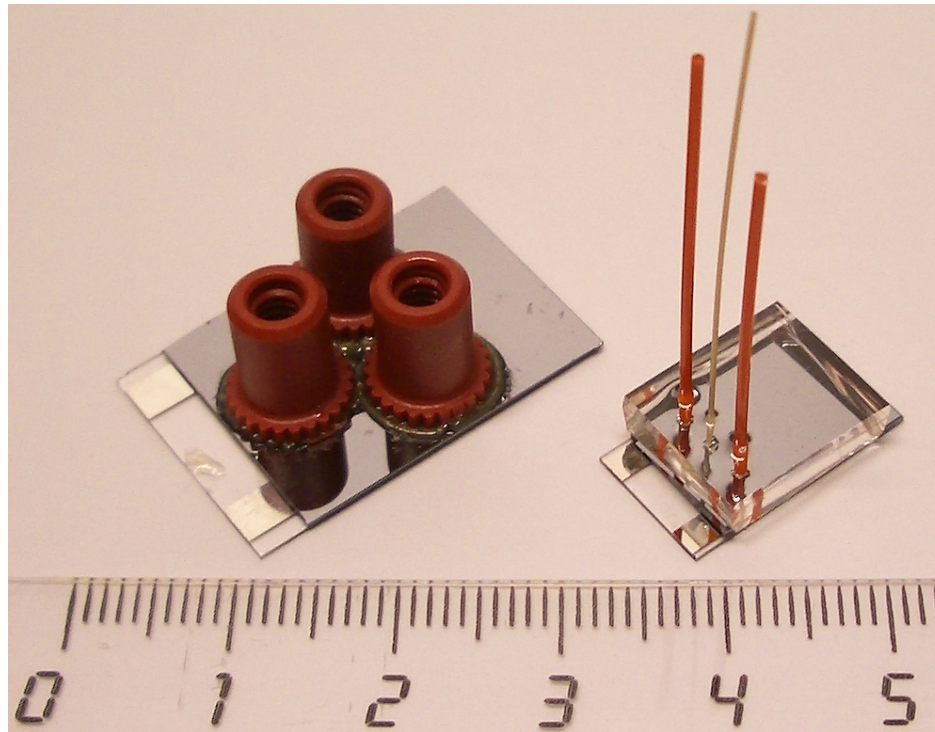


DRIE nozzle vs. wet etched nozzle



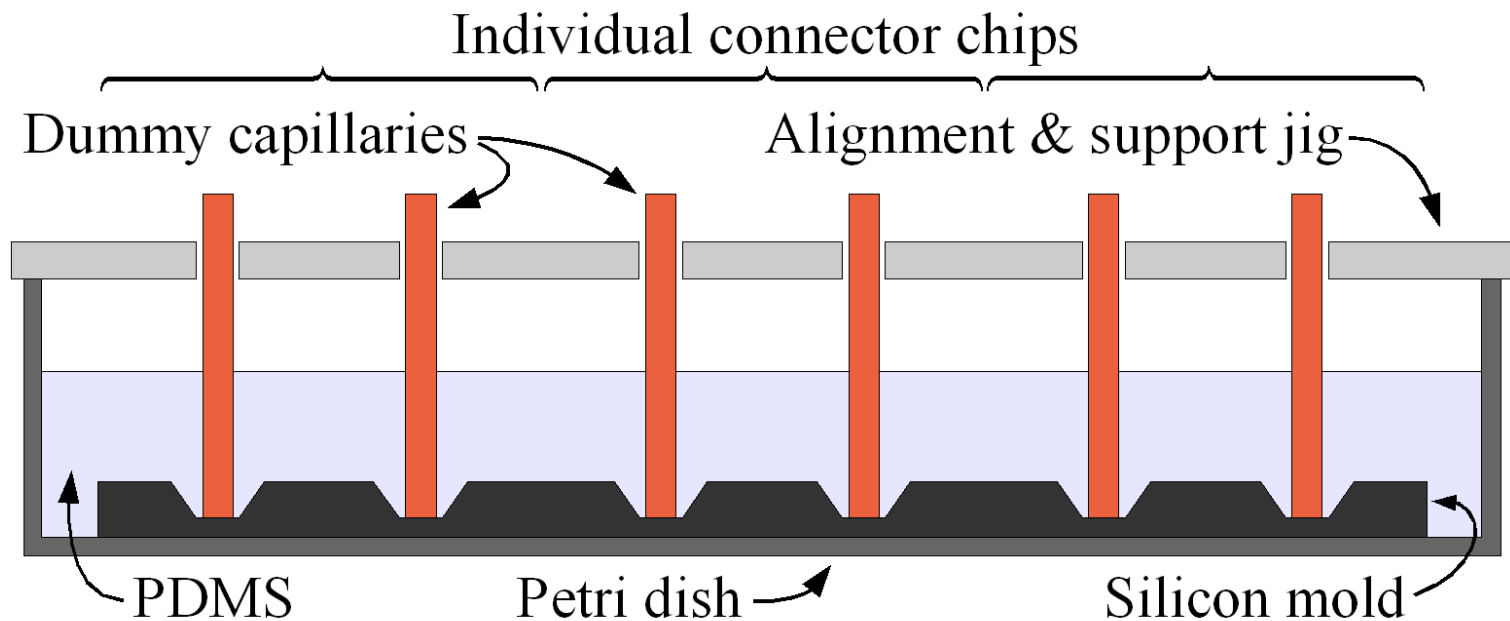


Fluidic connectors



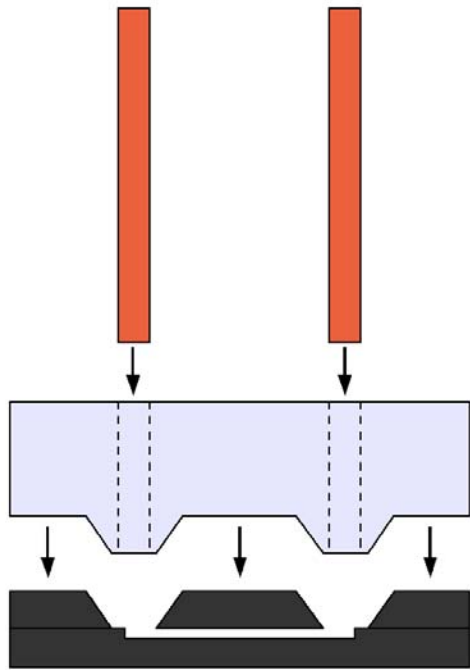


PDMS connector chip fabrication

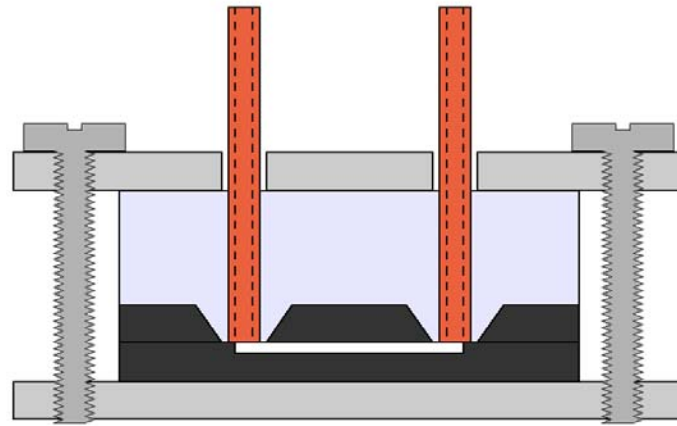




PDMS connector chip usage



(a)

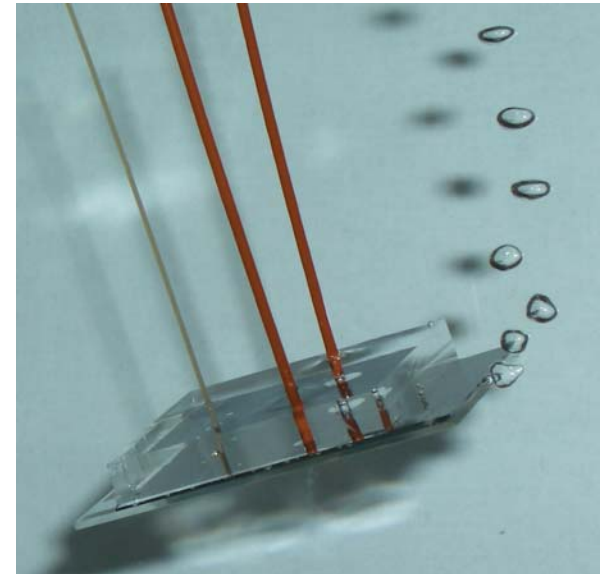


(b)



PDMS connector chip

- Detachable connector and tubing
- Pressure tolerance up to 190 kPa
- Simple fabrication
- Inexpensive
- Self-sealing
- No yield loss
- Reusable
- Multiple inlets
- Small surface area per inlet
- Small dead-volume





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